

Instructor's Biography

L. T. Nguyen is a Senior Engineering Manager in the Packaging Research Group at National Semiconductor Corp., working on various aspects of wafer-level packaging, lead-free and halogen-free, thermal measurement and modeling, design-for-manufacturability, design-for-reliability, precision analog, printed electronics, and MEMS. He received his Ph.D. in Mechanical Engineering from MIT, and has worked at IBM Research and Philips Research.

He co-edited two books on packaging, and has close to 200 publications. He has over 70 patents and invention disclosures. He is a Fellow of IEEE and ASME, and a Fulbright Scholar (Finland 2002). He is currently an Associate Editor for the IEEE Transactions on Advanced Packaging, IEEE Transactions on Components and Packaging Technologies, and IEEE Transactions on Electronics Packaging Manufacturing. He was a Guest Editor for the T-EPM for a special issue on Drop Testing, and the T-ADvP for two issues on Wafer Level Packaging. He received two Best of Conference Awards (27th IEMT 2002 and InterPack 2005) and eight IMAPS and IEMT Best of Session Conference Awards. Other awards include the 2003 Mahboob Khan Outstanding Mentor Award from the Semiconductor Research Corporation in recognition of contributions to student mentoring, research collaboration, and technology transfer, and the 2004 IEEE CPMT Outstanding Sustained Technical Contributions Award.

He has also been involved with an Engineering Council since 2002 to develop a comprehensive program to foster professional development, practical training, best practices sharing, mentoring, cross-training, and e-learning among more than 2,500 National Semiconductor engineers worldwide. These efforts were recognized with the IEEE Educational Activities Board Employer Professional Development Award (2005), the IEEE Region 6 Outstanding Corporate Engineering Community Service Award (2006), and the European Electronics Industry Elektra "Investing in People" Award (2006).